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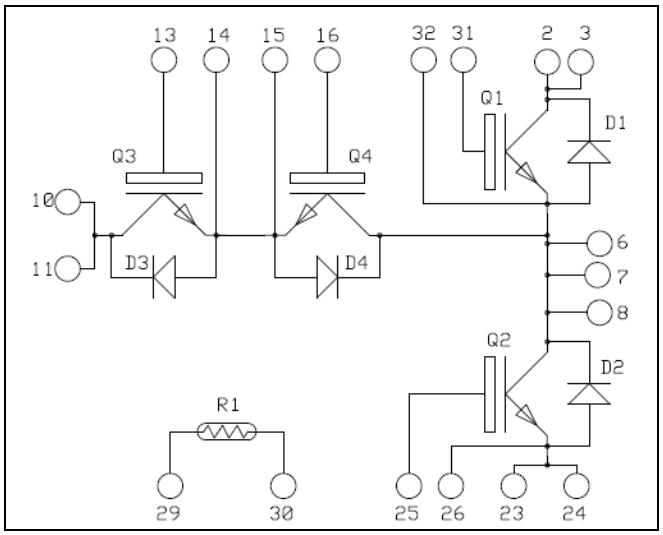
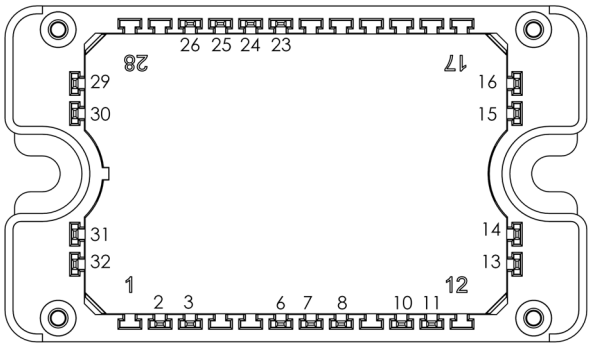
APTGLQ40HR120CT3G

Phase Leg & Dual Common Emitter Power Module

High speed Trench & Field Stop IGBT4 (Q1, Q2):
V_{CES} = 1200V ; I_C = 40A @ Tc = 80°C

Trench & Field Stop IGBT3 (Q3, Q4):
V_{CES} = 600V ; I_C = 50A @ Tc = 80°C





All multiple inputs and outputs must be shorted together
10/11 ; 23/24 ; 2/3 ; …

Application

- Solar converter
- Uninterruptible Power Supplies

Features

- ***Q1, Q2 High speed Trench + field Stop IGBT4***
  - Low voltage drop
  - Low tail current
- ***Q3, Q4 Trench + field Stop IGBT3***
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
- ***SiC Schottky Diode (D3, D4)***
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
  - Positive temperature coefficient on VF
- Kelvin emitter for easy drive
- Very low stray inductance
- High level of integration
- Internal thermistor for temperature monitoring

Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- Low profile
- RoHS Compliant

All ratings @ T_j = 25°C unless otherwise specified

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.
See application note APT0502 on www.microsemi.com

1. High speed Trench & Field Stop IGBT4 Phase Leg Q1&Q2 (per IGBT)

Absolute maximum ratings (per IGBT)

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{CES}	Collector - Emitter Breakdown Voltage		1200	V
I_C	Continuous Collector Current	T_C = 25°C	75	A
		T_C = 80°C	40	
I_{CM}	Pulsed Collector Current	T_C = 25°C	160	
V_{GE}	Gate – Emitter Voltage		±20	V
P_D	Maximum Power Dissipation		250	W
RBSOA	Reverse Bias Safe Operating Area	T_j = 150°C	80A @ 1100V	

Electrical Characteristics (per IGBT)

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{CES}	Zero Gate Voltage Collector Current	V_{GE} = 0V, V_{CE} = 1200V				100	µA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	V_{GE} =15V I_C = 40A	T_j = 25°C	1.7	2.05	2.4	V
			T_j = 150°C		2.6		
$V_{GE(th)}$	Gate Threshold Voltage	V_{GE} = V_{CE} , I_C = 1 mA		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	V_{GE} = 20V, V_{CE} = 0V				120	nA

Dynamic Characteristics (per IGBT)

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
C_{ies}	Input Capacitance	V_{GE} = 0V V_{CE} = 25V f = 1MHz			2300		pF
C_{oes}	Output Capacitance				150		
C_{res}	Reverse Transfer Capacitance				135		
Q_G	Gate charge	V_{GE} = 15V, I_C = 40A V_{CE} = 960V			185		nC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) V_{GE} = ±15V V_{Bus} = 600V I_C = 40A R_G = 12Ω			30		ns
T_r	Rise Time				57		
$T_{d(off)}$	Turn-off Delay Time				290		
T_f	Fall Time				16		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (150°C) V_{GE} = ±15V V_{Bus} = 600V I_C = 40A R_G = 12Ω			30		ns
T_r	Rise Time				49		
$T_{d(off)}$	Turn-off Delay Time				366		
T_f	Fall Time				48		
E_{on}	Turn on Energy	V_{GE} = ±15V V_{Bus} = 600V I_C = 40A R_G = 12Ω	T_j = 25°C		3.2		mJ
			T_j = 150°C		3.75		
E_{off}	Turn off Energy		T_j = 25°C		1.2		
			T_j = 150°C		2.25		
I_{sc}	Short Circuit data	V_{GE} ≤15V ; V_{Bus} = 600V t_p≤10µs ; T_j = 150°C			150		A
R_{thJC}	Junction to Case Thermal Resistance					0.6	°C/W

Diode ratings and characteristics (D1 & D2) (per diode)

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1200			V
I_{RM}	Maximum Reverse Leakage Current	V_R=1200V				100	µA
I_F	DC Forward Current		Tc = 80°C		25		A
V_F	Diode Forward Voltage	I_F = 25A			2.6	3.1	V
		I_F = 50A			3.2		
		I_F = 25A	T_j = 125°C		1.8		
t_{rr}	Reverse Recovery Time	I_F = 25A V_R = 667V di/dt =200A/µs	T_j = 25°C		320		ns
			T_j = 125°C		360		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		480		nC
			T_j = 125°C		1800		
R_{thJC}	Junction to Case Thermal Resistance					1.4	°C/W

2. Trench & Field Stop IGBT3 Dual common emitter Q3&Q4 (per IGBT)

Absolute maximum ratings (per IGBT)

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{CES}	Collector - Emitter Breakdown Voltage		600	V
I_C	Continuous Collector Current	T_C = 25°C	80	A
		T_C = 80°C	50	
I_{CM}	Pulsed Collector Current	T_C = 25°C	100	
V_{GE}	Gate – Emitter Voltage		±20	V
P_D	Maximum Power Dissipation	T_C = 25°C	176	W
RBSOA	Reverse Bias Safe Operating Area	T_J = 150°C	100A @ 550V	

Electrical Characteristics (per IGBT)

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{CES}	Zero Gate Voltage Collector Current	V_{GE} = 0V, V_{CE} = 600V				250	µA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	V_{GE} =15V I_C = 50A	T_j = 25°C		1.5	1.9	V
			T_j = 150°C		1.7		
$V_{GE(th)}$	Gate Threshold Voltage	V_{GE} = V_{CE} , I_C = 600µA		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	V_{GE} = 20V, V_{CE} = 0V				600	nA

Dynamic Characteristics (per IGBT)

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{ies}	Input Capacitance	V_{GE} = 0V V_{CE} = 25V f = 1MHz			3150		pF
C_{oes}	Output Capacitance				200		
C_{res}	Reverse Transfer Capacitance				95		
Q_G	Gate charge	V_{GE} = ±15V, I_C = 50A V_{CE} = 300V			500		nC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) V_{GE} = ±15V V_{Bus} = 300V I_C = 50A R_G = 8.2Ω			110		ns
T_r	Rise Time				45		
$T_{d(off)}$	Turn-off Delay Time				200		
T_f	Fall Time				40		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (150°C) V_{GE} = ±15V V_{Bus} = 300V I_C = 50A R_G = 8.2Ω			120		ns
T_r	Rise Time				50		
$T_{d(off)}$	Turn-off Delay Time				250		
T_f	Fall Time				60		
E_{on}	Turn-on Switching Energy	V_{GE} = ±15V V_{Bus} = 300V I_C = 50A R_G = 8.2Ω	T_j = 25°C		0.2		mJ
			T_j = 150°C		0.26		
E_{off}	Turn-off Switching Energy		T_j = 25°C		1.35		mJ
			T_j = 150°C		1.75		
I_{sc}	Short Circuit data	V_{GE} ≤15V ; V_{Bus} = 360V t_p ≤10µs ; T_j = 150°C			250		A
R_{thJC}	Junction to Case Thermal Resistance					0.85	°C/W

3. SiC diode ratings and characteristics (D3 & D4) (per diode)

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I_{RM}	Maximum Reverse Leakage Current	V_R = 600V	T_j = 25°C		10	60	µA
			T_j = 175°C		20	300	
I_F	DC Forward Current		Tc = 100°C		10		A
V_F	Diode Forward Voltage	I_F = 10A	T_j = 25°C		1.6	1.8	V
			T_j = 175°C		2	2.4	
Q_C	Total Capacitive Charge	I_F = 10A, V_R = 600V di/dt = 500A/µs			28		nC
C	Total Capacitance	f = 1MHz, V_R = 200V			65		pF
		f = 1MHz, V_R = 400V			50		
R_{thJC}	Junction to Case Thermal Resistance					2.5	°C/W

4. Thermal & package characteristics

Temperature sensor NTC

Symbol	*Characteristic*	*Min*	*Typ*	*Max*	*Unit*
R_{25}	Resistance @ 25°C		22		kΩ
$\Delta R_{25}/R_{25}$	Resistance tolerance			5	%
$\Delta B/B$	Beta tolerance			3	
$B_{25/100}$	T_{25} = 298.16 K		3980		K

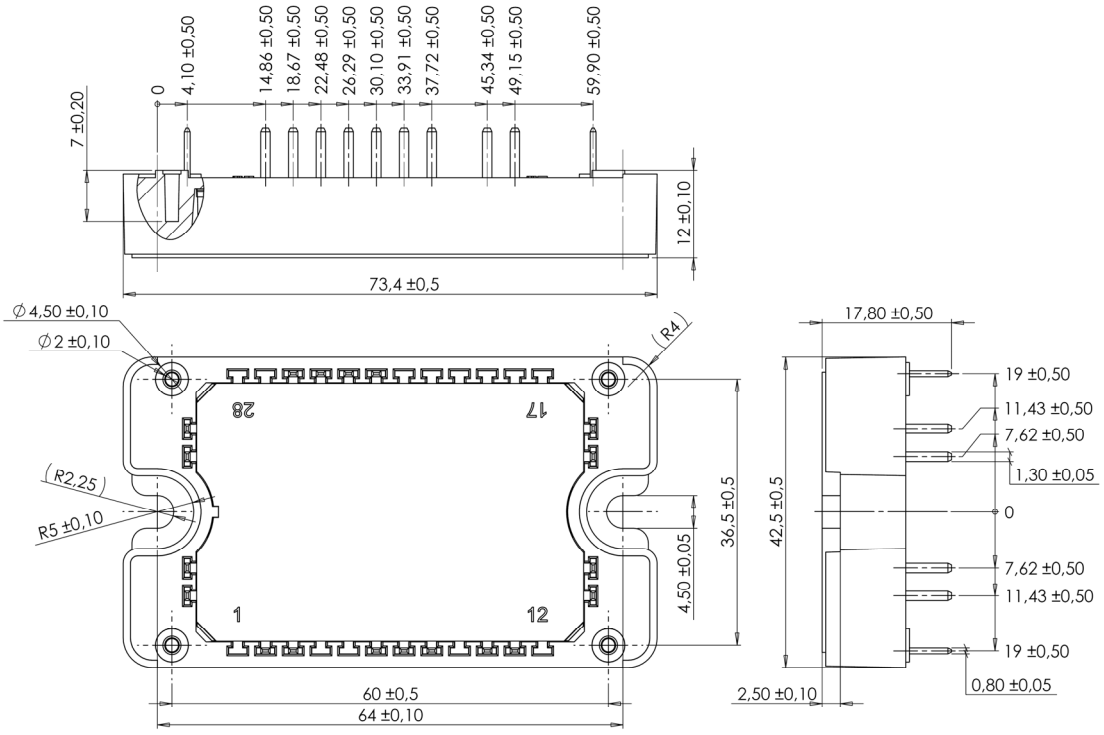
$$R_T = \frac{R_{25}}{\exp\left[B_{25/100}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature
R_T: Thermistor value at T

Thermal and package characteristics

Symbol	*Characteristic*			*Min*	*Typ*	*Max*	*Unit*
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		175	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M4	2		3	N.m
Wt	Package Weight					110	g

SP3F Package outline (dimensions in mm)

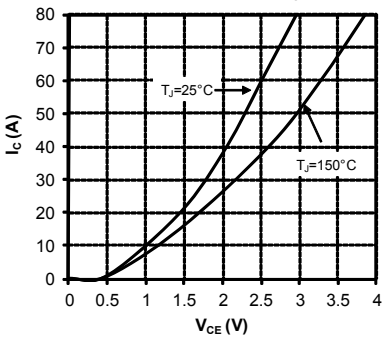


See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

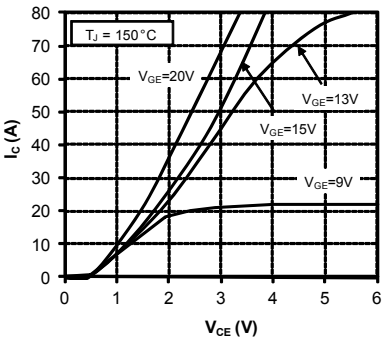
5. Typical performance curve

Q1, Q2 High speed Trench + field stop IGBT4 + CR1 & CR2 diode characteristics

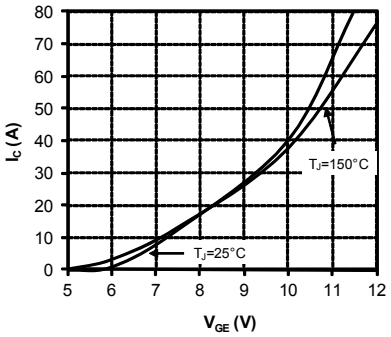
Output Characteristics (V_{GE}=15V)



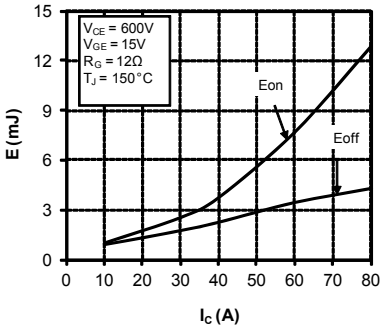
Output Characteristics



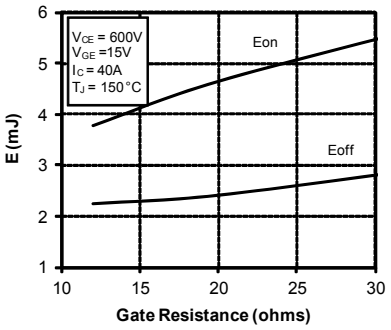
Transfert Characteristics



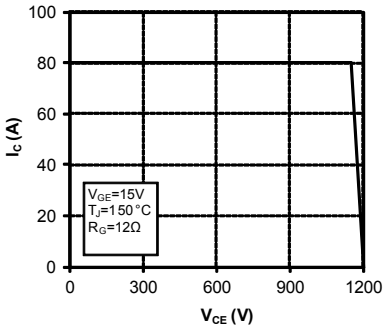
Energy losses vs Collector Current



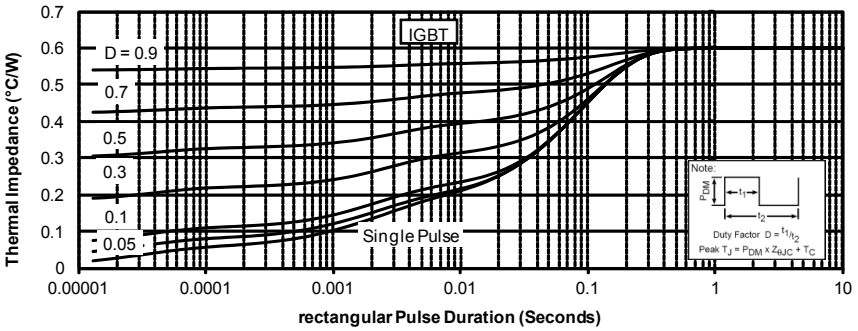
Switching Energy Losses vs Gate Resistance

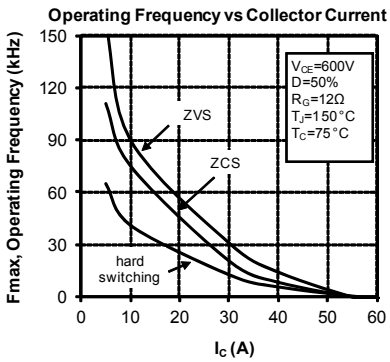


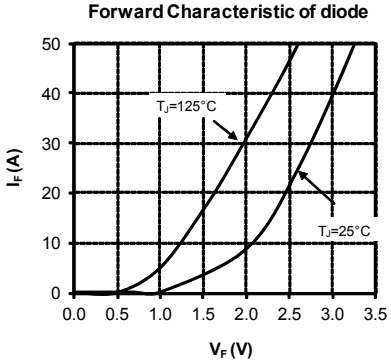
Reverse Bias Safe Operating Area

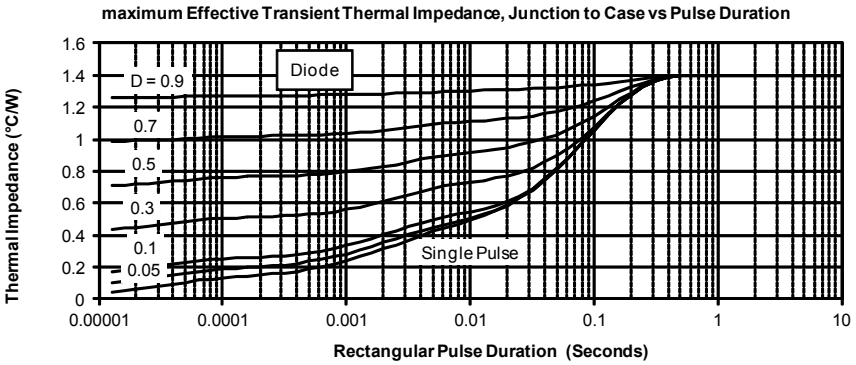


maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration

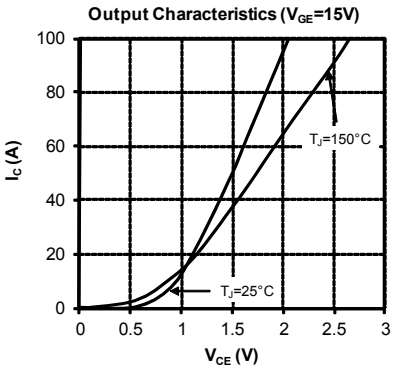


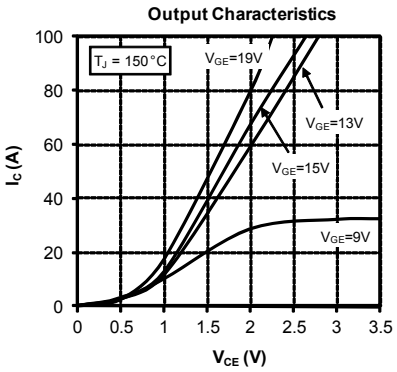


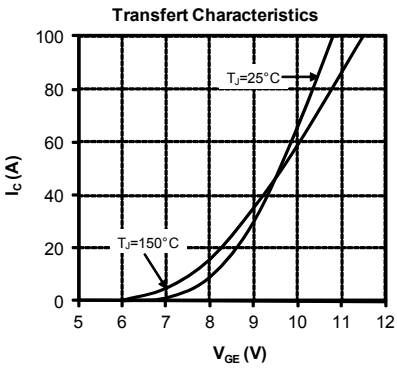


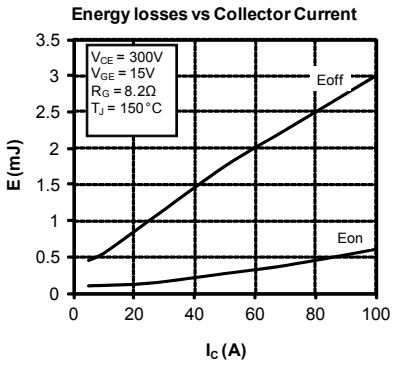


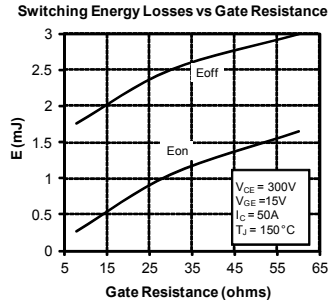
Q3, Q4 Trench + field stop IGBT3

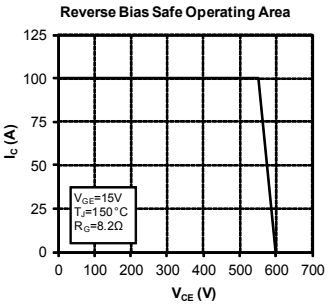


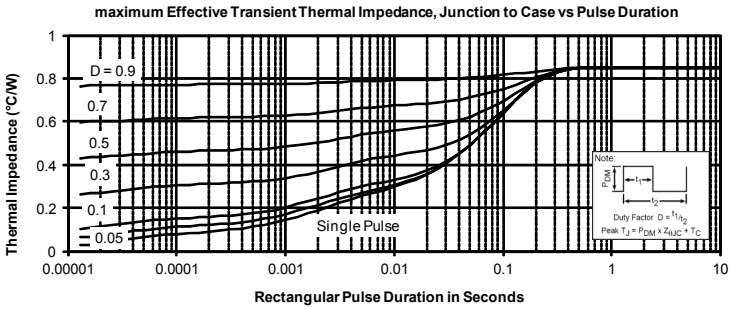




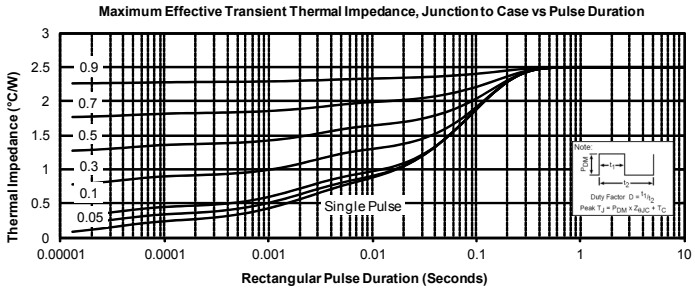


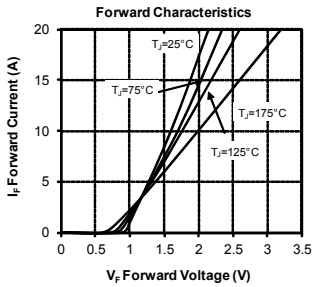


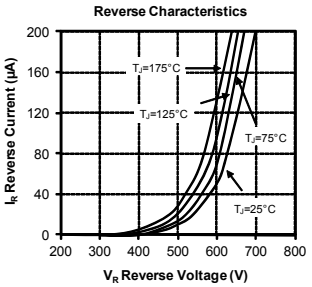


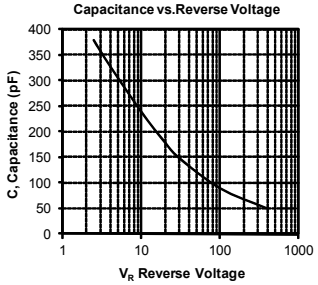


CR3 & CR4 SiC diode characteristics









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